Abstract:

Process for cleaning a semiconductor wafer using a cleaning solution

The invention relates to a process for cleaning a semiconductor wafer using a cleaning solution containing an ammonium-alkaline component in an initial composition, wherein the semiconductor wafer is brought into contact with the cleaning solution in an individual-wafer treatment, and in the course of cleaning hydrogen fluoride is added as further component to the cleaning solution, and the cleaning solution has at the end of cleaning a composition that differs from the initial composition.

(No figure)